ON Semiconductor®

Final Product/Process Change Notification

Document #: FPCN22910X
Issue Date: 08 Aug 2020

Title of Change:	CM1624-08DE & CM1693-04DE Transfer from TWC and SPEL to ISMF and SBN.
Proposed First Ship date:	15 Nov 2020 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office or MohdAzrul.Abdullah@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or PCN.samples@onsemi.com Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Nicky.Siu@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Affected products will be identified with marking code from new plant
Change Category:	Assembly Change, Test Change
Change Sub-Category(s):	Material Change, Datasheet/Product Doc change, Manufacturing Site Change

Sites Affected:

ON Semiconductor Sites	**External Foundry/Subcon Sites**
ON Semiconductor Seremban, Malaysia	Chipbond Technology Hsinchu, Taiwan
	SPEL Semiconductor Limited

Description and Purpose:

Transfer assembly and test from SPEL to SBN, which includes change in Leadframe design, mold material and bond wire.

Transfer the Backgrind/Backmetal site from TWC to ON Semiconductor, ISMF.

	Before Change Description	**After Change Description**
Bond Wire	0.9 MIL AU	0.8 MIL AU
Mold Compound	MC G770HCD HF	MC SUMITOMO G760
Backgrind/Backmetal	CHIPBOND TECHNOLOGY CORP(TWC)	ON Semiconductor, ISMF
Assembly Site	SPEL	ON Semiconductor, Seremban
Test Site	SPEL	ON Semiconductor, Seremban

No package dimension change and no product performance change.

All the capacitance condition are guarantee by design and the datasheet was updated to add this statement.

Reliability Data Summary:

QV DEVICE NAME : CM1624-08DE
RMS : 58877
PACKAGE : UDFN16 3.3x1.35

Test	Specification	Condition	Interval	Results
H3TRB	JESD22-A108	Ta=125°C, 100% max rated V	1008hrs	0/80
HTSL	JESD22-A103	Ta= 150°C	1008hrs	0/80
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2min	15000cyc	0/84
TC	JESD22-A104	Ta= -55°C to +150°C	1000cyc	0/84
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/84
PC	J-STD-020 JESD-A113	MSL1 @ 260 °C		
RSH	JESD22- B106	Ta = 260C, 10 sec		0/30
SD	JSTD002	Ta = 245C, 5 sec		0/15

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal****.*

Part Number	Qualification Vehicle
CM1624-08DE	CM1624-08DE
CM1693-04DE	CM1693-04DE